

## Supplementary Information

### Effects of Temperature on Microstructures of MSA-type Electroplating Solution: A Coarse-grained Molecular Dynamics Simulation

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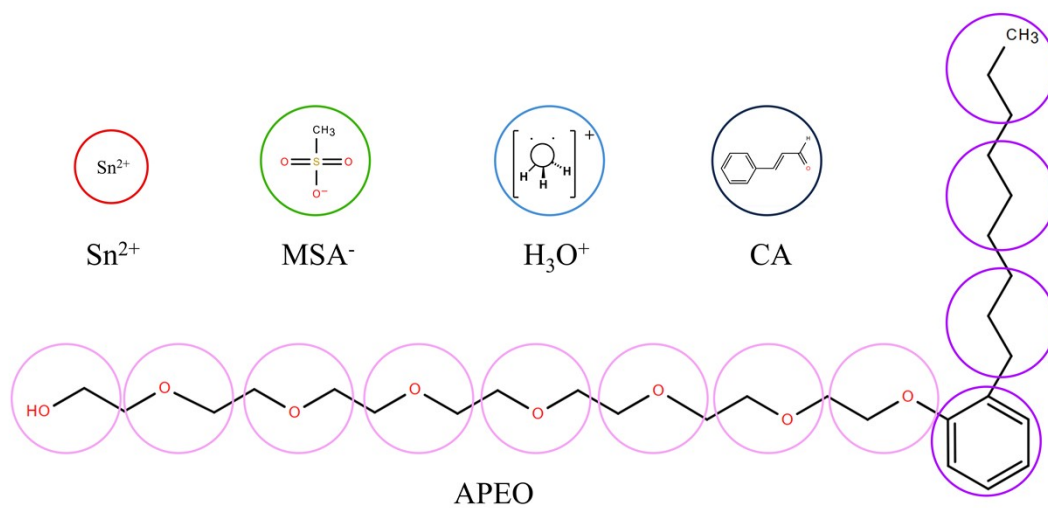
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**Fig. S1** The chemical structures of simulated molecules.